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Serial No. 10/502,506

PU010288

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Inventor: Eric Stephen Carlsgaard  
Application No.: 10/502,506  
Filed: July 23, 2004  
Title: Flip Chip Die Bond Pads, Die Bond Pad Placement and Routing Optimization  
Examiner: Huynh, Andy  
Art Unit: 2818  
Customer No.: 24498

**AMENDMENT AFTER FINAL**

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated October 19, 2006, for which a shortened statutory period of three months for response ending January 19, 2007, the following comments are submitted and reconsideration of the claim rejections is respectfully requested.

The Applicants submit that in view of the attached Certificate of Mailing, this response is timely.

**Listing of the Claims** begin on page 2 of this paper.

**Remarks/Arguments** begin on page 5 of this paper.